

2827



Yeo, et al.

Serial No.: 10/078,718

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**For: Enhanced Chip Scale Package
For Wire Bond Dies**

Attorney's Docket No. 4795-002

Thai, Luan C.
Examiner
Group Art Unit: 2827

Raleigh, North Carolina

April 11, 2003

**Box Non-Fee Amendment
Commissioner for Patents
Washington, D.C. 20231**

RESPONSE TO NON-FINAL OFFICE ACTION MAILED JANUARY 14, 2003

Dear Sir:

Applicants submit the following response in reply to the Office Action mailed on the above date. The Commissioner is hereby authorized to charge any fees or charges due in association with this response to Deposit Account 18-1167.